



Customer Information Notification

201508004I

Issue Date: 29-Aug-2015
Effective Date: 29-Sep-2015

Here's your personalized quality information concerning products Digi-Key purchased from NXP.
For detailed information we invite you to view this notification online



QUALITY

Management Summary

NXP will introduce new design lighter packing reels using less material.

Change Category

<input type="checkbox"/> Wafer Fab process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Electrical spec./Test coverage	<input type="checkbox"/> Mechanical Specification
<input type="checkbox"/> Wafer Fab location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Test Location	<input checked="" type="checkbox"/> Packing/Shipping/Labeling

NXP will introduce new design lighter packing reels at APP.

Information Notification

As announced through GN 201310002 NXP will introduce a new design reels using less material. Materials used will not change.

Through this CIN NXP communicates the introduction of one reel at our assembly site APP.

These reels have been tested and fulfil our packing requirements and are in compliance with EIA-481D and IEC60286-3. Conversion for the products in this phase will start per end of September 2015, to be finalized later in 2015. Stock of reels with current design will be used up before delivery of products in light weight reels will start.

In the conversion period current and light weight reels might be mixed, but viewing the fact that they are fully compatible, this will not hamper processing at customers.

For detailed information we invite you to view this notification online (see link above) where a file is attached which indicates what the change looks like and what has been tested to release this.

Why do we issue this Information Notification

This change enables environmental improvement by reducing waste materials.

Identification of Affected Products

Products from APP can be identified by the letter m on the third line of marking and on the packing label (if space permits).

Impact

No impact to the product's functionality anticipated. The major dimensions will not change, reels are fully compatible with the reels currently used.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

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